

**Please amend the claims as follows:**

1. (Amended) A method for forming an electrically conductive layer having patterns for semiconductor devices, comprising the steps of:

providing a substrate;

forming a non-functional insulation layer on the substrate;

forming a functional insulation layer on the non-functional insulation layer, the insulation layer having predetermined functional groups;

forming a patterned polymer layer having the patterns on the functional insulation layer;

etching the functional insulation layer in accordance with the patterns of the patterned polymer layer to create a patterned insulation layer;

stripping the patterned polymer layer to expose the patterned insulation layer;

treating the patterned insulation layer with a coupling agent reacting with the predetermined functional groups;

treating the patterned insulation layer with a catalyst-containing solution; and

depositing electrically conductive material on the patterned insulation layer.

8. (Amended) A method for forming an electronically conductive layer having patterns for semiconductor devices, comprises the steps of:

providing a substrate;

forming an insulation layer on the substrate, the insulation layer having predetermined functional groups;

forming a patterned polymer layer having the patterns on the insulation layer;

etching the insulation layer in accordance with the patterns of the patterned polymer layer  
to create a patterned insulation layer;  
stripping the patterned polymer layer to expose the patterned insulation layer;  
treating the patterned insulation layer with a coupling agent reacting with the  
predetermined functional groups;  
treating the patterned insulation layer with a catalyst-containing solution; and  
depositing electrically conductive material on the patterned insulation layer, wherein the  
patterned polymer layer comprises solvent soluble polyimide.

15. (Amended) A method for forming an electrically conductive layer having patterns  
for semiconductor devices, comprising the steps of:  
providing a substrate;  
forming a non-functional insulation layer on the substrate;  
forming a functional insulation layer on the non-functional insulation layer, the  
functional insulation layer having predetermined functional groups;  
forming a patterned polymer layer having the patterns on the functional insulation layer,  
the patterned polymer having a coupling agent;  
etching the functional insulation layer in accordance with the patterns of the patterned  
polymer layer to create a patterned insulation layer;  
stripping the patterned polymer layer to expose the patterned insulation layer;  
treating the patterned insulation layer with a catalyst-containing solution; and  
depositing electrically conductive material on the patterned insulation layer.

22. (New) A method for forming an electrically conductive layer having patterns for semiconductor devices, comprising the steps of:

providing a substrate;

forming a non-functional insulation layer on the substrate;

forming a functional insulation layer on the non-functional insulation layer, the functional insulation layer having predetermined functional groups;

forming a patterned polymer layer having the patterns on the functional insulation layer, the patterned polymer comprises solvent soluble polyimide;

etching the functional insulation layer in accordance with the patterns of the patterned polymer layer to create a patterned insulation layer;

stripping the patterned polymer layer to expose the patterned insulation layer;

treating the patterned insulation layer with a catalyst-containing solution; and

depositing electrically conductive material on the patterned insulation layer;